

MATERIAL DECLARATION SHEET



Material Number	PTVS6-380C-TH			
Product Line	Semiconductor Products			
Compliance Date	September 1 st 2014			
RoHS Compliant	Yes	MSL	Not Applicable	

No.	Construction Element (subpart)	Homogenous Material	Material Weight (g)	Homogenous Material/ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart Mass % of total unit wt.
1	Encapsulation	Epoxy Resin	0.676900	Bisphenol Copolymer Alumina Trihydrate Fused Silica Hydrated Iron Oxide Titanium Dioxide Melamine Cyanurate Amine Adduct	1675-54-3 25085-99-8 14464-46-1 40039-93-8 51274-00-1 13463-67-7 Trade Secret	60.00 15.00 20.00 1.50 1.50 1.50 0.50	5.06 1.27 1.69 0.13 0.13 0.13 0.04	8.44
2	Electrodes	Copper	5.503238	Copper Silver Other	7440-50-8 7440-22-4 -	99.10 0.40 0.50	68.01 0.27 0.34	68.63
3	Terminations	Copper	0.470046	Copper Other	7440-50-8 -	99.50 0.50	5.83 0.03	5.86
4	Termination Finish	Silver	0.002110	Silver	7440-22-4	100.00	0.03	0.03
5	Chip	Silicon Die	0.634359	Silicon Aluminium Nickel Gold	7440-21-3 7429-90-5 7440-02-0 7440-57-5	85.86 4.95 8.76 0.42	6.79 0.39 0.69 0.03	7.91
6	Die Attach	Solder	0.367416	Lead Tin Silver	7439-92-1 7440-31-5 7440-22-4	92.50 5.00 2.50	4.24 0.23 0.11	4.58
7	Die Coating	Silicone	0.364812	Polysiloxane Chromium Sesquioxide Fumed Silica Filler	63148-62-9 1308-38-9 112945-52-5 trade secret	22.11 5.67 11.11 61.11	1.01 0.26 0.51 2.78	4.55
Total Weight			8.018881					